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C

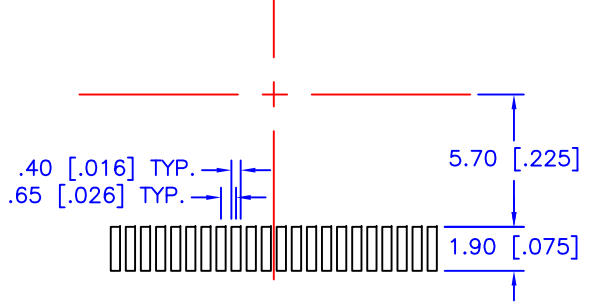
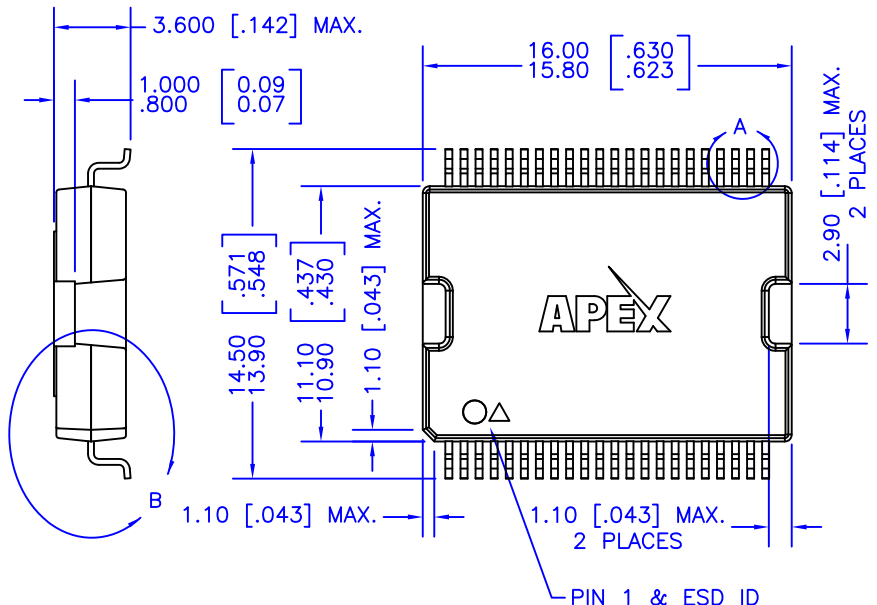
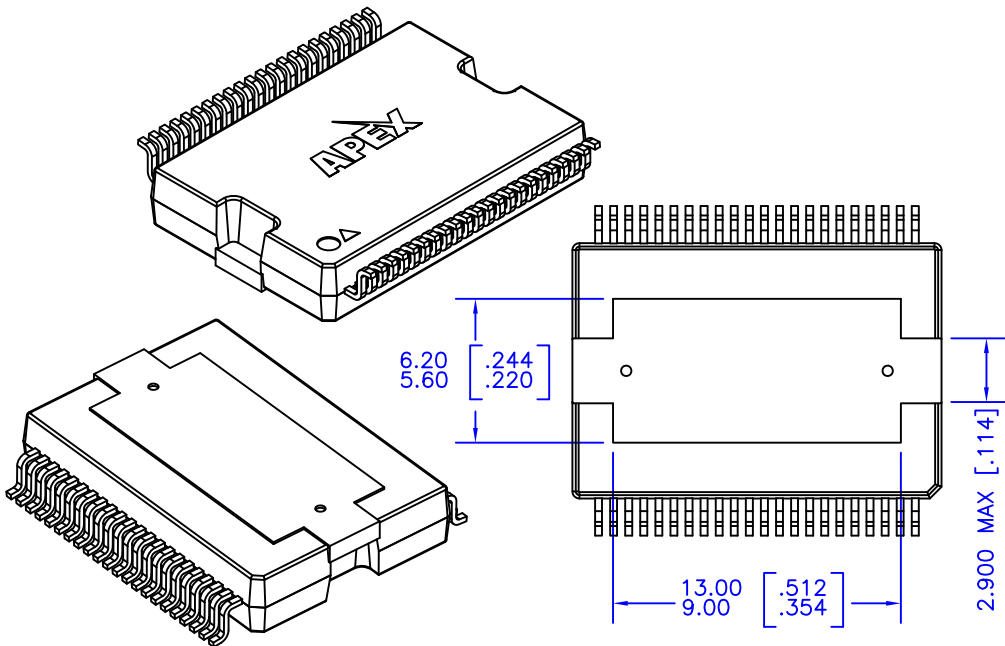
C

B

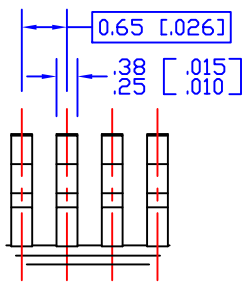
B

A

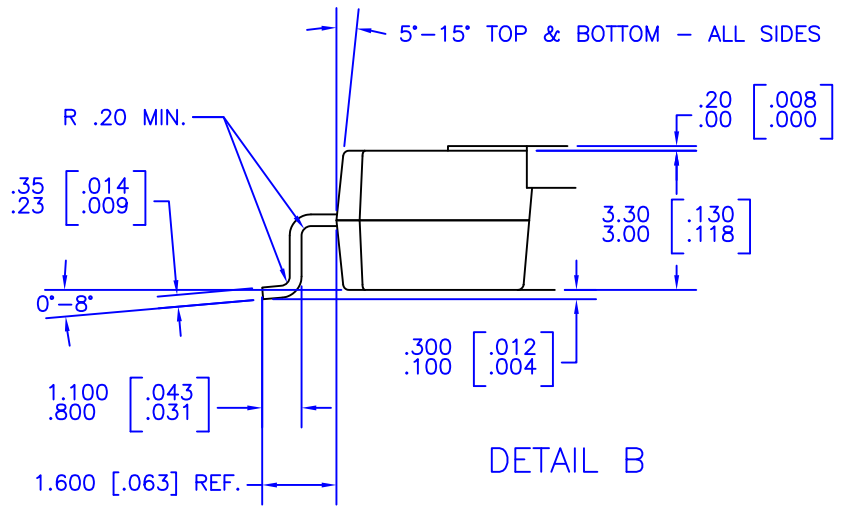
A



Surface Mount Layout



DETAIL A



DETAIL B

NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Pins & Heat Slug: C19400 & C10200 copper with plated finish.
5. Mold compound: Epoxy
6. Package weight: .086 oz. [2.44 g]
7. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED .XX = ±.01 [0.254] .XXX = ±.005 [0.127] ANG. = ±5°	 <small>WIRETECHNOLOGY</small> <small>PRECISION • POWER • ANALOG</small>	TITLE: JEDEC MO-166, 44-pin HSOP SLUG-UP	MODEL:
		SUBJECT: PACKAGE OUTLINE	HU
ENGINEER: D-M	DRAWN BY: R.MOR	DCA: 13236	SH. OF 1 1
FILENAME: HU			REV: C
DATE: 29MAY13			

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